

International Application No.: PCT/JP2005/012403  
U.S. Patent Application No.: Unknown  
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**IN THE ABSTRACT:**

Please replace the Abstract of the Disclosure originally filed with the above-identified patent application with the following new Abstract of the Disclosure:

## ABSTRACT OF THE DISCLOSURE

A composite ceramic substrate includes a ceramic substrate having surface-mounted components mounted thereon, external terminal electrodes connecting wiring patterns disposed on the ceramic substrate and surface electrodes of a motherboard, and a convex leg portion made of resin and arranged such that an end surface supports the external terminal electrodes, and the external terminal electrodes are connected to the wiring patterns via a via-hole conductor provided in the leg portion.